





# ***ELECTROPLATING***

For the Metallurgist, Engineer and Chemist

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## **Electroplating for the Metallurgist, Engineer and Chemist**

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## Contents

CHAPTER	PAGE
Introduction . . . . .	5
1. The Mechanism of Electrodeposition . . . . .	9
2. The Laws and Characteristics of Plating Baths	17
3. The Control of a Plating Bath . . . . .	27
4. The Deposit . . . . .	35
5. The Preparatory Steps . . . . .	44
6. Cadmium Cyanide Baths . . . . .	54
7. Chromium Baths . . . . .	59
8. Acid Copper Baths . . . . .	67
9. Copper Cyanide Baths . . . . .	75
10. Iron Plating . . . . .	85
11. Lead Plating . . . . .	89
12. Nickel Plating . . . . .	94
13. Silver Plating . . . . .	103
14. Acid Tin Baths . . . . .	108
15. Alkaline Tin Baths . . . . .	112
16. Acid Zinc Baths . . . . .	117
17. Zinc Cyanide Baths . . . . .	121
18. Electroplated Alloys . . . . .	128
19. Copper Plating for Selective Carburization . .	150
20. Diffusion Coatings . . . . .	157
21. Selection of a Plating Bath . . . . .	162
22. Continuous Plating . . . . .	168
23. Applications of Electroplating . . . . .	174
24. Plating-Bath Troubles . . . . .	179
25. Analytical Methods for Plating Baths . . . .	207
Appendix . . . . .	233
Glossary . . . . .	241
Index . . . . .	247



## Introduction

The metallurgist and engineer are well acquainted with electrodeposition as a means of refining metal. This process, known as electrorefining, became widely accepted because of the high purity of the metal it produced. The very term "electrolytic copper" has become synonymous with metal of high purity. The metallurgist, in becoming familiar with this process, has learned that a certain metal will tend to go into solution, under the influence of current, exclusive of other metals in the anode. Thus, if an anode containing copper and gold is electrolyzed in a sulfuric acid electrolyte, the copper will go into solution and the gold will remain behind as an anode sludge. He has also learned that a certain metal will deposit, under the influence of current, exclusive of other metals in the electrolyte. Thus, if a copper sulfate electrolyte, such as would be obtained by the electrolysis previously mentioned, were to contain tin, the copper would still deposit exclusive of the tin. The copper deposit obtained by such a process would be rough and nodular but would be sufficiently sound to permit its use as a source of high-purity copper.

The process of electrorefining illustrates the fundamental requirements for electrodeposition; namely, an anode or positively charged electrode, a cathode or negatively charged electrode, an electrolyte or means of carrying current and a source of current. If these fundamental requirements are met, electrodeposition may take place, but the resulting deposit will not necessarily be of value.

If a metal salt is picked at random and current is applied to a solution of the salt, the results obtained will be varied. If the salt solution contains sodium chloride, only hydrogen will develop at the cathode. If a solution contains lead acetate, lead

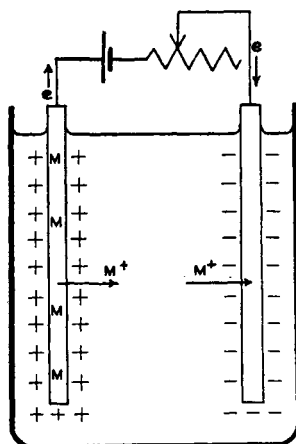


FIGURE 1  
*Electrodeposition*

will deposit, but the deposit will appear as long crystals extending into the bath. If a solution contains stannic sulfate, the stannic ions will be reduced to stannous ions at the cathode and, at least for a short time and at a low current density, neither tin nor hydrogen will deposit. If a solution contains chromic acid, only hydrogen will develop; but if a small amount of sulfuric acid is added to the electrolyte, then chromium will deposit in addition to hydrogen.

By experimentation with solutions of metal salts, baths can be developed that will produce satisfactory deposits. A great many experiments are usually required and often it is necessary to study the effect of a host of organic substances known as addition agents. By experimentation and study, new baths have been developed to fill specific needs. For example, a deposit that is satisfactory for electrorefining may not be satisfactory for electroforming. A deposit that is satisfactory for electroforming may not be satisfactory for electroplating.

Electroplating is a process of electrodeposition by which a thin, smooth, sound metallic deposit is produced over a basis metal. This definition sets electroplating apart from the other processes of electrodeposition even though the requirements of the definition are not met in every case.

In this book, the fundamentals of electroplating will be briefly considered. A number of plating baths will then be discussed. The book is written for the trained metallurgist, engineer and chemist, with a good background in science but only a slight acquaintance with electroplating. Thus, we intend to go into more detail on the fundamentals than is required



for an experienced plater or an electrochemist but considerably less detail than is required for one trained without a general knowledge of science.



## CHAPTER 1

### The Mechanism of Electrodeposition

#### *The Electrolyte*

The process of electrodeposition is one in which electric current is carried across an electrolyte and in which a substance is deposited at one of the electrodes.

The electrolyte is the medium that carries the current by means of ions. The ability of a solvent, especially water, to ionize substances dissolved in it, *i.e.*, to split them into components, that carry positive and negative charges makes electrolysis possible. The electricity is carried across the electrolyte by the charged ions, and products of electrolysis appear at the electrodes. This is a result of the positively charged ions being attracted to the negatively charged cathode while the negatively charged ions travel toward the positively charged anode. The charges of the ions are then neutralized by the charges on the electrodes and the products of the electrolysis appear at the electrodes.

The electrolyte is a conducting medium in which the flow of electric current is accomplished by the movement of matter. It is usually a substance that gives rise to ions on dissolution in a solvent, but a fused salt may also act as an electrolyte. If more than one ion is present, carrying a positive charge, several reactions are possible at the negatively charged cathode, although usually only one product of electrolysis appears. Each electrode reaction takes place at a specific voltage and the most positive metal ion will deposit at the cathode.

Any liquid or solution that contains ions can be used as an electrolyte. The large majority of commercial electrolytes, however, use water as the solvent and are, therefore, called aque-

## 10 *Electroplating for Metallurgist, Engineer, Chemist*

ous electrolytes. Fused salts, which are a class of nonaqueous electrolytes, find their greatest use in the electrolytic production of metals such as sodium, magnesium and aluminum. Fused-salt electrolytes are also used in the electrolytic cleaning of metals. Another type of nonaqueous electrolytes are solutions in organic solvents. These have been used for experimental electroplating of aluminum but have not as yet been applied commercially.

The extensive use of water as the solvent in the electroplating industry is due to its cheapness and abundance and to the fact that practically all the common salts used in the process are very soluble in water.

In this book, the aqueous electrolytes alone will be considered. The term electroplating will be occasionally simplified to plating, which is known to cover electroplating.

### *The Cathode*

The plater is primarily interested in the reaction that takes place at the cathode since this is where deposits are produced. The potential at which this reaction takes place is called the deposition potential. This potential can be measured readily in the laboratory, but it is neither convenient nor desirable to measure it in the plating tank. The reaction at the cathode is much easier to follow by a knowledge of the quantity of current that reaches the cathode. If, in addition, the plater has some knowledge as to the distribution of the current over the cathode, he may then have some idea of how the plated article will be coated with metal. He will be able to predict the time required to produce a desired thickness of deposit and also have an idea of how the thickness will vary from one area to another of the plated piece.

Unfortunately, it is difficult to make accurate predictions regarding the distribution of metal over the cathode. In practice, the quantity of current is controlled and the current is allowed to flow for a definite period of time after which the local thickness of metal on the plated piece is measured. If an

undesirable distribution of metal is obtained, adjustments are made in the racking or positioning of the pieces or of the anodes. In some cases, chemical adjustment of the electrolyte may improve the metal distribution.

The current allowed to flow to the cathode is in proportion to the area being plated, so that the current is expressed as current density or quantity of current per unit area. In commercial plating, the current density is expressed as amperes per square foot.

Occasionally, a plating tank is controlled by voltage. This procedure is less satisfactory than control by current density, since the tank voltage is affected by many factors other than the reaction taking place at the cathode. Tank voltage, however, is very easily measured and often gives information about changes in the plating process, such as a reduction in conducting salt content, or polarization of the anode. Plating control by tank voltage is satisfactorily used in cases where the cathode area is difficult to measure, such as in barrel plating.

#### *The Anode*

The reactions taking place at the anode are almost independent of the reactions occurring at the cathode. The position of the anodes naturally has much to do with the distribution of current at the cathode, but the anodes usually operate best at a range of current densities that can be changed independently of the cathode current density by changing the anode area.

#### *The Balanced Bath*

A plating bath can be operated successfully for long periods of time if the composition of the bath is not changed too rapidly. Such changes are primarily due to:

1. Chemical decomposition
2. Incomplete electrode reactions
3. Drag-in or drag-out

The bath stability can best be illustrated by consideration of several typical baths.

## 12 *Electroplating for Metallurgist, Engineer, Chemist*

An acid copper bath is relatively easy to control because there is very little tendency for chemical decomposition and the reactions at the electrodes are essentially complete. This means that the electrolyte is chemically stable and that for every chemical equivalent of copper dissolved at the anode, there is a chemical equivalent of copper deposited at the cathode. Nevertheless, the bath cannot be continuously and satisfactorily operated without control, since solution is lost from the system by drag-out every time a rack is removed. Control is further complicated in that glue is generally added to the bath to produce a finely crystalline deposit. The glue is not stable and must be closely controlled. This bath is typical of many acid baths where the major factor in control is the addition agent used; in this case, the glue.

An alkaline tin bath is not a typical alkaline bath, but it is a good example of a bath where care is required to maintain solution balance.

In the alkaline tin bath, the electrode reactions are not complete, i.e., the anode and cathode efficiencies are less than 100 per cent. In addition to depositing tin, hydrogen is evolved at the cathode. And in addition to tin being dissolved, oxygen is given off at the anode. To make the problem more complex, the bath undergoes continuous chemical decomposition and the anodes must be maintained with an oxide film at all times. If the oxide film is not present, or is too thick, troubles set in that throw the bath out of balance or even cause a deposit to form that is not acceptable. The bath can be controlled by regulation of bath temperature, cathode-current density, anode-current density and by chemical analysis and proper chemical additions. The bath voltage is responsive to changes at the anodes; and since the bath is sensitive to anode changes, the voltage may be used as an aid to bath control.

A plating bath should always be kept within prescribed chemical limits whether or not the bath composition is difficult to maintain. The bath should also be used in such a way that a minimum of chemical additions is required. It is very rare

that a bath does not require additions for long periods, although this condition is approached where the anode efficiency is slightly higher than the cathode efficiency. Such a bath would be a perfectly balanced bath, but even in this case, drag-out would eventually remove a sufficient amount of one of the essential chemicals so that chemical additions would be required. Since additions are required to all baths, it is best to make them frequently and in small amounts, so that chemical limits are easily held. Addition of large quantities of chemicals to the plating bath often leads to trouble. For example, for a large addition of chemicals, a small error in chemical analysis is liable to result in a concentration exceeding the chemical limits on the bath. Moreover, the chemicals often contain impurities that are not harmful for small additions, but that require electrolysis with dummy cathodes before the bath may be used, if the additions are large.

#### *The Equilibrium Potential*

It is well to settle a few points regarding the equilibrium potential before considering some of the details of the plating process.

The well-known series of potentials for electrochemical reactions is shown in Table 1. This series has also been called the electrochemical series or the electromotive force series of elements. It is a reliable point for reference; however, it can be highly misleading if it is used as a definite guide. These potentials are equilibrium potentials. They were measured under conditions where no current was flowing. They were measured for definite quantities of dissolved salt present and at a standard temperature to obtain comparable values.

Hydrogen is taken as the reference point on the electrochemical scale and is arbitrarily assigned a value of zero. The metal ions whose voltage is listed as positive are more reactive than the hydrogen ion when they are present in equivalent chemical quantities, whereas the metal ions having a negative voltage are less reactive than the hydrogen ion. Thus as we go

## Index

### A

- Abrasion resistance, 178
- Accelerated corrosion tests, 234
- Acid baths, cadmium strike, 58
  - chromium, 59
  - copper, 67
  - lead, 89
  - lead-tin, 142
  - lead-tin-copper, 143
  - nickel-cobalt, 145
  - tin, 108
  - zinc, 117
- Acids, analytical methods, 212
- Activated carbon, 44, 100
- Active, definition, 241
- Addition agents, alloy deposition, 130, 142, 145
  - cadmium, 54
  - copper, acid, 69
  - cyanide, 80
  - iron, 85
  - lead, 90
  - nickel, 100
  - silver, 104
  - tin, acid, 109
- Adhesion, definition, 241
- tests, 234
- Agitation, copper baths, 70
- effects, 83
- silver baths, 105
- Airplane bearings, lead alloys, 176
- silver, 104
- silver alloys, 176
- tin alloys, 176
- Alkali cleaning, 49
  - determination, 228
  - in cadmium bath, 55
  - in copper bath, 79
  - in silver bath, 104
  - in tin bath, 112
  - in zinc bath, 123
- Alkaline baths, brass, 185
  - bronze, 139
  - cadmium, 54, 186
  - copper, 75, 191
  - gold, 196
  - silver, 103, 198
  - tin, 112, 199
  - zinc, 121, 201
- Alkaline cleaner, 50, 238
- Alloy, anodes, 63, 142, 146, 148
  - baths, electrochemistry, 134
  - deposition, 128
  - effect of variables, 135
- Alloy deposits, brass, 133, 185
  - bronze, 139
  - cast vs. electrodeposited, 37
  - copper-tin-zinc, 133, 144
  - lead-tin, 142
  - lead-tin-copper, 143
  - nickel-cobalt, 145
  - silver-lead, 128
  - solder, 133
  - speculum, 133, 141
  - tin base, 141
  - tin-zinc, 147
- Alloy formation, binary phase
  - diagram, 158
  - bond line, 73



- Alloy formation (*Cont.*):  
 solid solution, 128
- Aluminum, anodized, 100  
 chloride in acid zinc, 118  
 deposit, 166  
 plating on, 99
- Ammonium chloride, acid zinc,  
 117  
 chloride, nickel, 100  
 thiosulfate brightener, 104
- Ampere, definition, 17  
 hour, definition, 241  
 second, 17
- Analyses, 207  
 cathode efficiency, 210  
 centrifuge, 211  
 colorimetric, 211  
 electrolytic, 210  
 gravimetric, 210  
 pH meter, 211  
 polarographic, 211  
 specific, 212  
 still required, 212  
 volumetric, 209
- Analytical methods, 209  
 acids, 212  
   chromic, 213  
   fluoboric, 214  
   free, 214  
   hydrochloric, 215  
   sulfuric, 215  
 ammonia, 215  
 cadmium, 216  
 carbonate, 217  
 chloride, 218  
 chromium, 218  
 copper, 218  
 cyanide (free), 220  
 cyanide (total), 221  
 gelatin, 222  
 gold, 222  
 indium, 224  
 iron, 224
- Analytical methods (*Cont.*):  
 lead, 225  
 nickel, 225  
 resorcinol, 226  
 Rochelle salt, 226  
 silver, 227  
 sodium acetate, 228  
 sodium cyanide, 229  
 sodium hydroxide, 228  
 sodium thiocyanate, 229  
 sulfate, 229  
 tin, 230  
 zinc, 231
- Anode, 241  
 alloy, 63, 142, 146, 148  
 arrangement, 20  
 bagging, 98  
 reactions, 11  
 sludge, 241
- Anodic cleaning, 50  
 coatings, 100  
 pickling, 51
- Antimonial lead, 63  
 Antimony deposit, 166  
 Antipit agent, 80  
 Applications, plating, 174  
 Atomic, definition, 241  
 forces, 73  
 weight, definition, 241
- B
- Balanced bath, 11  
 definition, 241
- Barrel plating, 19  
 cathode efficiency, 19
- Base box (tin plate), 169, 241  
 metal, 241
- Basic copper compound, 69  
 salt, 40
- Basis metal, definition, 242
- Bath, chemical limits, 12  
 definition, 242

- Bath (*Cont.*):  
  preparation, 45  
  voltage, 23  
Baumé, definition, 242  
Bent cathode test, 233, 242  
Bimetallic alloys, 128  
Binary systems, 160  
Blacklight test, 233  
Blistering, 152  
Bond, definition, 242  
  factors affecting, 152  
  strength, 73  
  tests, 165  
Boric acid, 89  
  buffer, 95  
  in nickel, 100  
Brass, anodes, 136  
  bath, 136, 185  
  bath analysis, 216  
Bright alloy, 144  
  dips, 53  
  nickel, 94  
  plating range, 124  
Brightener, 39  
  cadmium, 55  
  copper, 80  
  nickel, 100  
  silver, 104  
  zinc, 124  
Brinell hardness, 42  
Bronze, 139  
Buffer action, nickel, 100  
Buildup, salvage, 163  
Burrs, effects, 152
- C
- Cadmium alloys  
  anodes, 187  
  bath, 55, 186  
  compounds, 55  
  cyanide, 54  
  determination, 220
- Cadmium (*Cont.*):  
  oxide, 55  
  plating, 57  
  protective value, 54  
Calorizing, 157  
Carbon disulfide in silver bath,  
  104  
Carbonate in cyanide baths, 125  
  determination, 217  
  removal, 125  
Carburization, 150  
  diffusion coatings, 157  
Cathode, definition, 242  
  efficiency, 18, 242  
  measurement, 19  
  polarization, 22  
  alloy deposition, 134  
  potential, 10  
Cathodic cleaning, 50  
Centrifuge analytical method,  
  233  
Ceramic tanks, 69  
Characteristics of deposit, 35  
Charcoal powder, iron bath, 87  
Chemical equivalent, 12  
  pickling, definition, 242  
Chromic acid, 62, 188  
  solutions, specific gravity, 64  
Chromium baths, 62, 188  
  analysis, 214  
  applications, 61  
  characteristics, 60  
  plating range test, 31  
Cleaners, alkaline, 53  
Coating, definition, 242  
Cobalt chloride, 146  
  nickel alloy, 145  
Colloids, migration, 90  
Colorimeter, 233  
Combined cyanide, definition, 56  
Compatible metals, 242  
Complexes, 132  
Complexion, 242

- Compound formation, 158  
 Conduction, 172  
 Conductivity, cleaning effect, 32  
   control, 31  
   definition, 242  
   meter, 233  
 Contaminants, definition, 242  
 Continuous strip plating, 172  
 Control, 34  
   methods, 27  
 Convection current, definition, 242  
   stratification, 92  
 Conversion tables, 234  
 Copper alloys, 144  
   anodes, 71, 83  
   anodic etch, 71  
   basis metal, effect on structure, 73  
   cathode efficiencies, 77  
   chemical displacement, 72  
   contaminants, removal, 81  
   determination, 218  
   grain size, 69  
   sulfate, 68, 190  
 Corroding, 157  
 Corrosion tests, 234  
 Cracks in basis metal, 151  
 Cresol, 109  
   sulfonic acid, 109  
 Cresylic acid, 109  
 Crystal form, 40  
   lattice, 42  
   size, 129  
   structure, 38  
 Current, 242  
   density, 25, 242  
   range, 236  
   distribution, 10, 17  
   efficiency, 17  
 Cyanide analysis, 220  
   baths, brass, 136, 185  
   cadmium, 54, 186  
 Cyanide (*Cont.*):  
   baths (*Cont.*):  
     copper, 75, 191  
     gold, 196  
     silver, 103, 198  
     zinc, 121, 201  
   combined, definition, 242  
   cyanometric analysis, 220  
   determination, 220
- ### D
- Decomposition potential, 23  
 definition, 243  
 Degreasing, definition, 243  
   methods, 50  
 Density, Baumé, 242  
   chromic acid, 64, 236  
   copper sulfate, 236  
   various baths, 236  
 Deposit properties, 37  
   cast vs. plated, 37  
   factors affecting, 34  
 Deposition potential, 15  
 Diffusion coatings, calorizing, 157  
   carburizing, 157  
   chromizing, 157  
   definition, 243  
   ihrigizing, 157  
   nitriding, 157  
   sherardizing, 157  
   siliconizing, 157  
   stannizing, 157  
 Distribution, current, 10, 17  
   metal, 20  
 Drag-in, definition, 243  
 Drag-out, definition, 243  
   tanks, recovery, 53, 168  
 Drop test, 233  
 Ductility, chromium, 60  
   iron, 85  
   nickel, 101  
 Dull nickel, 94

## E

- Economic applications, 174  
Electrochemical equivalents, 239  
  formulas, 239  
  potential series, 13  
  series, definition, 243  
  yields, 240  
Electrode, anode, 11  
  cathode, 10  
  current-voltage curve, 23  
  positioning, 20  
  reaction, 9  
  definition, 243  
Electrodeposition, 5  
  definition, 243  
Electroforming, 68  
  definition, 243  
Electrolysis, definition, 243  
Electrolytes, aqueous, 10  
  definition, 243  
  nonaqueous, 10  
Electrolytic alkaline cleaning,  
  definition, 243  
  copper anodes, 5, 83  
  definition, 243  
  pickling, 243  
  tin plate, 108  
Electrolytic analysis, 210  
  cadmium, 216  
  copper, 218  
  gold, 223  
Electrometric analysis, silver,  
  227  
Electromotive force, 13  
  series, 13  
Electronegative, definition, 14,  
  244  
Electroplating, 244  
Electropositive, 14, 244  
Electrorefining, definition, 244  
Electrotinning, 108, 169  
  definition, 244  
Embrittlement, 41  
Engineering applications, 175  
Equilibrium, measurement, 13  
  potential, definition, 244  
Etch, definition, 244  
Etching reagents, 235  
Excessive polarization, defini-  
  tion, 244  
Experimental plating, 165
- F
- Faraday, 17  
  definition, 244  
Ferric iron in iron bath, 86  
Ferrocyanide in copper cyanide  
  baths, 80  
  removal, 80  
  titration, cadmium, 216  
  zinc, 231  
Ferrostan process, 170  
Ferrous ammonium sulfate, 87  
Ferrous carbonate, 87  
Ferrous (iron) bath, 85  
Ferroxyl test, porosity, 233  
Fluoborate, lead, 89, 142  
  tin, 142  
Fluoboric acid, 89  
Fluoride ion, 90  
Fluosilicate, lead, 89  
Fluosilicic acid, 89  
Foaming agent, 236  
Formaldehyde, nickel-cobalt, 145  
Formulas, plating, 54  
Formulation, definition, 244  
Free cyanide, definition, 242  
  determination, copper, 220  
  silver, 221  
Freezing carbonates, 125  
Fused salt electrolytes, 10
- G
- Gelatin in lead-tin bath, 142  
  in tin bath, 103

- General bath troubles, 181  
 Glucose in acid zinc, 117  
 Glue, colloidal properties, 90  
   effect on deposit, 12  
   in copper bath, 69  
   in lead bath, 90  
   in tin bath, 109  
 Gold bath, 196  
   determination, 222  
 Gram atomic weight, definition, 244  
   equivalent weight, definition, 17, 244  
 Gravimetric analysis, 210  
 Gravity, definition, 244
- H
- Hard chromium, 59  
   water precipitates, 105  
 Hardness, chromium, 60  
   current density effects, 41  
   nickel, 101  
   of various metals, 42  
   temperature effects, 41  
 Heat treating, 157  
 Hexavalent chromium, 60  
   determination, 214  
 High concentration copper bath, 80  
   speed copper bath, 80  
 Hot dip tinning, 108  
 Hull cell, 233  
   definition, 244  
 Humidity cabinet, 233  
 Hydrochloric acid, 51  
 Hydrofluoric acid, 89  
 Hydrogen, definition, 244  
   embrittlement, 41  
   ion replenishment, 24  
   overvoltage, 24  
     definition, 244  
   polarization, 15
- Hydrogen peroxide, nickel, 96  
   tin, 115  
 Hydrometer, 31  
 Hydroxyl ion, 31  
 Hypo, 104
- I
- Ihrigizing, 157  
 Immersion deposition, 100  
 Impurities, cadmium bath, 57  
   copper, 80  
   nickel, 95  
     effects-removal, 95  
 Indium, determination, 224  
 Induction brightening tin, 172  
 Industrial chromium plating, 59  
 Inhibitors, 90  
 Inorganic, definition, 244  
 Insoluble anodes, chromium, 59  
   copper, 78  
   tin, 115  
   zinc, 126  
 Intermediate phases, 159  
 Intermetallic compounds, 128  
 Ion, definition, 244  
   diffusion, 24  
 Ionization, definition, 244  
   substances, 9  
 Iron anodes, 78, 85, 115, 127  
   bath, 85  
   build-up of worn parts, 85  
   determination, 224  
   in chrome bath, 63  
   in nickel bath, 98  
 Iron-cobalt alloy, 128  
 Iron-nickel alloy, 128
- K
- Knoop indenter, hardness, 38

- L
- Laminated deposits, causes, 42  
  nickel, 101
- Large additions, 13
- Lattice, 128
- Lead anodes, 92  
  crystal growth, 90  
  determination, 225  
  fluoborate, 89  
  fluoride, 90  
  fluosilicate, 89  
  indium alloy, 89  
  lining, 63  
  peroxide, 63  
  plating, 89  
  sulfamate, 89  
  tin alloy, 142  
  tin-copper alloy, 143
- Limited solid solubility, 159
- Limiting current density, definition, 242
- Lines of current flow, 19
- Local thickness tests, 233
- Low cathode efficiency, causes, 184  
  free acid, effects, 183  
  free cyanide, effects, 183  
  pH, effect on nickel, 202
- M
- Magna-gage, 233
- Magnetic methods, thickness, 233
- Manganese chloride in iron bath, 85
- Mechanical agitation, 35
- Mercury compounds in anodes, 124  
  in zinc bath, 123
- Metal complex, definition, 244  
  concentration in alloy deposition, 130  
  displacement, 14  
  distribution, 19  
  impurities, 31  
  tests, 28  
  ions, 13  
  relative activity, 15  
  salt, definition, 244
- Methods, analytical, 207
- Methyl orange, 214
- Migration of colloids, 90
- Mil, definition, 244
- Mineral acids, definition, 245
- Mol (Mole), definition, 245
- N
- $\beta$ -Naphthol, 109
- Nickel ammonium sulfate, 101  
  applications, 95  
  bath, 94  
    Baumé, 97  
  chloride, 95  
  cobalt alloys, 128, 145  
  current density range, 238  
  deposition, 94  
  deposits, properties, 101  
  determination, 225  
  double salt, 101  
  pH control, 97  
  plating, 94  
    aluminum, 99  
    copper-brass, 94, 99  
    steel, 94, 99  
    zinc, 99  
  plating range, 238  
  properties, 101  
  protective value, 94  
  purification, 99  
  resistivity (bath), 237  
  specific gravity (bath), 237

- Nickel (*Cont.*):  
 strike, 235  
 sulfate, 95  
 zinc alloys, 157  
 Nitrates in silver, 104  
 Nitric acid, 51  
 Nitriding, 157  
 Noble metal, definition, 245  
 system, 245  
 Nonaqueous, definition, 245  
 Normal polarization, definition, 245
- O
- Organic coatings, 164  
 definition, 245  
 electrolytes, 10  
 Overlay, 73  
 Overvoltage, 24  
 definition, 245  
 Oxide films, 12  
 Oxidizing pickle, 107  
 Oxygen at the anode, 76
- P
- Parting compounds, 38  
 Passive, definition, 245  
 Passivity, 53  
 Periodic reverse current, 83  
 Permanganate titration, iron, 225  
 Rochelle salt, 227  
 pH control, 31  
 effects, 85, 94  
 iron bath, 85  
 meter, 233  
 nickel bath, 94  
 Phase diagram, 129  
 Phenol, 109  
 Phenolsulfonic acid, tin bath, 109  
 Phonograph records, 68  
 Physical properties, chromium, 60  
 grain size, 37  
 hardness, 38  
 initial layer, 38  
 nickel, 101  
 thickness vs. structure, 38  
 Pickling aluminum, 52  
 definition, 245  
 effects, 51  
 electrolytic, 51  
 Pitting, nickel, 96  
 Plate, definition, 245  
 distribution, 184  
 Plating bath formulas, brass, 136, 185  
 bath troubles, 179  
 bronze, 140  
 cadmium, 55, 186  
 chromium, 59, 188  
 copper, acid, 67, 190  
 cyanide, high efficiency, 80, 193, 194  
 Rochelle, 79, 191  
 gold, 196  
 iron, 85, 198  
 laboratory, 164  
 lead, 89, 197  
 lead-tin, 142  
 lead-tin-copper, 144  
 nickel, 94, 202  
 cobalt, 145  
 quality, 24  
 range, 238, 245  
 rate, calculation, 18  
 silver, 103, 198  
 tests, 233  
 tin, acid, 108  
 alkaline, 112, 199  
 tin-zinc, 149  
 zinc, acid, 117, 200  
 cyanide, 121, 201

- Polarization, definition, 245  
description, 22  
measurement, 23
- Polarograph, 233
- Poor adhesion, 181  
anode corrosion, 183
- Porosity, 44  
tests, 151, 233
- Potassium argentocyanide, 103  
carbonate, removal, 81  
nitrate (in silver), 104  
stannate, 115  
vs. sodium cyanide, 81
- Potential system, definition, 245
- Precipitation (analysis), 211
- Preparatory steps, electroplating, 44
- Primary salt, 39, 245
- Properties of baths, 167
- Purification, copper bath, 81  
nickel bath, 96  
various baths, 44  
zinc bath, 126
- Q
- Quantitative analysis, 209
- R
- Racks, 48
- Recrystallization, 40
- Red brass, 185
- Research applications, 175
- Resistivity, cleaners, 238  
various plating baths, 236
- Resorcinol, 109, 142  
analysis, 226
- Reverse current, cleaning, 50  
periodic, 83
- Rinsing, 52
- Robbing, 21
- Rochelle, copper bath, 75  
salt, 76
- Rough deposits, causes, 182
- Rubber adhesion, brass, 135  
lined tanks, 68
- S
- Salt spray test, 233
- Sandwich effect, 245
- Scale effects, 245
- Selection, baths, 162  
deposits, 162
- Semiautomatic machines, 169
- Separate anodes in alkaline tin, 115  
in copper bath, 77  
in cyanide zinc, 127
- Shadowing, 20
- Sherardizing, 157
- Shot blasting, 153
- Siliconizing, 157
- Silver anodes, bagging, 105  
bath, 103, 198  
cyanide, 103  
depleting control, 32  
deposition, 103  
determination, 227  
ionization, 131  
strike, 32
- Single electrode potential, 238
- Slivers, 152
- Soap, soak cleaning, 235
- Sodium acetate, 112, 117  
determination, 228  
cadmicyanide, 55  
carbonate  
determination, 217  
removal, 80  
cyanide  
determination, 220  
effect on bright range, 124  
formate, 145  
hexametaphosphate, 235  
hydroxide, determination, 228



- Sodium (*Cont.*):  
 metasilicate, 235  
 stannate, 112  
 stannite, 113  
 sulfate, 100  
 vs. potassium cyanide, 81  
 zinc cyanide, 122  
 zincate, 122
- Soft chromium, 60
- Soil removal, 49
- Solid diffusion, 158  
 solubility, 159  
 solution, alloys, 128  
 formation, 158
- Solidus, 160
- Solvent, cleaning, 50  
 definition, 245
- Specific gravity, alkaline cleaner, 237  
 various baths, 236
- Specification plating, definition, 246
- Speculum metal, 141
- Spotty deposits, causes, 183
- Stannate bath, 112
- Stannic, definition, 246  
 sulfate, 109
- Stannizing, 157
- Stannous, definition, 246  
 fluoborate, 142  
 sulfate, 108  
 tin, determination, 230
- Steel anodes, 77, 115, 127
- Stray currents, 63
- Stress in deposits, 40
- Strike baths, 234
- Striking, 53  
 definition, 246
- Structure, basis metal effect, 74
- Sulfamate lead, 93
- Sulfate, determination, 229  
 ratio, chromium, 60
- Sulfocyanate (thiocyanate) determination, 229
- Sulfuric acid, 51  
 determination, 215
- Surface active materials-cleaners, 235
- Surface films, definition, 246
- T
- Tank linings, 63  
 materials, 86  
 voltage, 11
- Temperature effects, alloy deposition, 137, 140, 146  
 brass, 185  
 chromium, 189  
 copper, 190  
 gold, 197  
 iron, 198  
 nickel, 203  
 tin, 200
- Tensile strength, nickel, 101
- Ternary system, 160
- Terne plate, 142
- Thickness measurements, 233
- Thiocyanate, determination, 229  
 titration, silver, 227
- Thiosulfate, titration, chromium, 218  
 copper, 219
- Throwing power, 25  
 chromium, 61  
 tin, 115
- Tin alloys, bronze, 140  
 lead, 142  
 lead-copper, 143  
 speculum, 141  
 anodes, 113  
 deposition, acid, 108  
 alkaline, 112  
 determination, 230
- Tin bath, acid, 108

- Tin (*Cont.*):  
 alkaline, 112, 199  
 Total cyanide, definition, 56  
 determination, 221  
 Treeing, lead, 90  
 tin, 109  
 Trisodium phosphate, 79, 236,  
 238  
 Trivalent chromium, 63  
 definition, 246  
 determination, 218  
 Tumbling, 153  
 Tungsten alloy, 166
- U
- Uranium nitrate (zinc titra-  
 tion), 231
- V
- Valence, definition, 17, 246  
 Vapor degreasing, 246  
 Vickers hardness, 101  
 Voltage, current curve, 23  
 effect on tin anodes, 12  
 tank, control, 11
- W
- Water break, cleaning, 49  
 high efficiency copper, 196  
 Watts nickel bath, 100  
 Wax masking, 34
- Wear resistance, 93, 133, 134  
 Wetting agents, cleaner, 235  
 copper, 80  
 Wire plating, 172
- Z
- Zinc activity, 126  
 anodes, 124  
 baths, acid, 117, 200  
 characteristics, 121  
 cyanide, 121, 201  
 mercury, 123  
 resistivity, 237  
 specific gravity, 237  
 bright deposits, 124  
 coatings, protective value, 117  
 copper alloy (brass), 135  
 copper-tin alloy, 132, 144  
 cyanide ratio, 124  
 cyanide strike, 120  
 deposition, acid, 117  
 cyanide, 121  
 determination, 231  
 iron, compound layers, 117  
 metal spraying, 117  
 nickel baths, 203  
 oxide, 127  
 pink (brass), 185  
 sherardizing, 117  
 sulfate, 117  
 tin alloy, 147  
 Zincate, 122





